

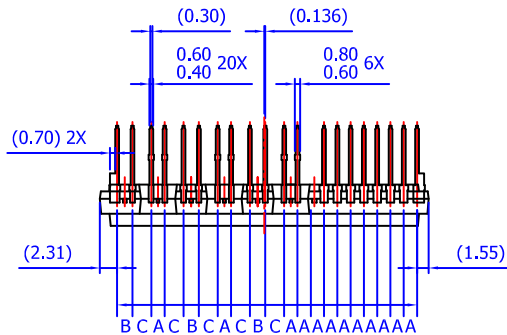
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



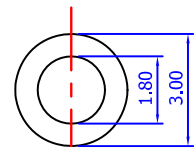
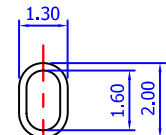
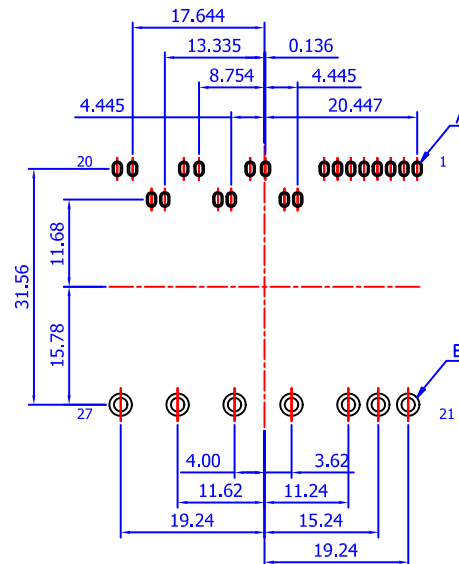
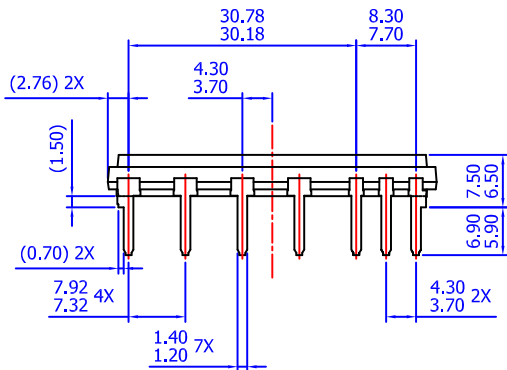
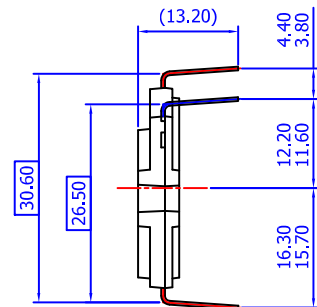
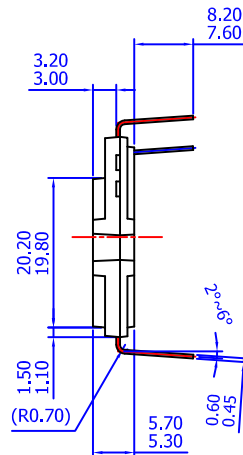
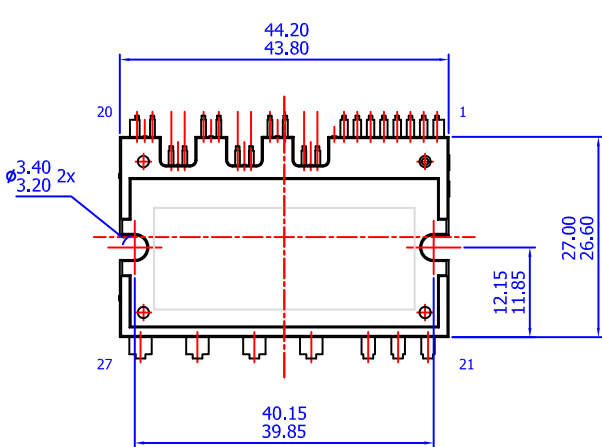
SPMBA-027 / PDD STD, SPM27-BA CASE MODFG ISSUE O

DATE 31 JAN 2017



LEAD PITCH (TOLERANCE : ±0.30)

- A : 1.778
- B : 2.050
- C : 2.531



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE

LAND PATTERN RECOMMENDATIONS

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPMBA-027 / PDD STD, SPM27-BA	PAGE 1 OF 2

